

X2-Class HiPerFET™ Power MOSFET

IXFK100N65X2 IXFX100N65X2

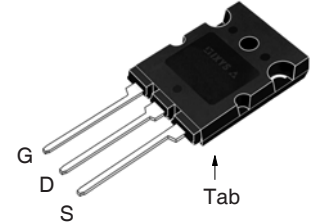
$V_{DSS} = 650V$
 $I_{D25} = 100A$
 $R_{DS(on)} \leq 30m\Omega$

N-Channel Enhancement Mode
 Avalanche Rated
 Fast Intrinsic Diode

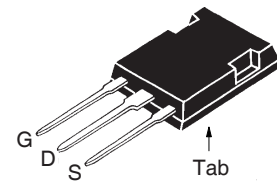


| Symbol | Test Conditions | Maximum Ratings | |
|---------------|--|------------------|------------|
| V_{DSS} | $T_J = 25^\circ C$ to $150^\circ C$ | 650 | V |
| V_{DGR} | $T_J = 25^\circ C$ to $150^\circ C$, $R_{GS} = 1M\Omega$ | 650 | V |
| V_{GSS} | Continuous | ± 30 | V |
| V_{GSM} | Transient | ± 40 | V |
| I_{D25} | $T_C = 25^\circ C$ | 100 | A |
| I_{DM} | $T_C = 25^\circ C$, Pulse Width Limited by T_{JM} | 200 | A |
| I_A | $T_C = 25^\circ C$ | 15 | A |
| E_{AS} | $T_C = 25^\circ C$ | 3.5 | J |
| P_D | $T_C = 25^\circ C$ | 1040 | W |
| dv/dt | $I_S \leq I_{DM}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ C$ | 50 | V/ns |
| T_J | | -55 ... +150 | $^\circ C$ |
| T_{JM} | | 150 | $^\circ C$ |
| T_{stg} | | -55 ... +150 | $^\circ C$ |
| T_L | Maximum Lead Temperature for Soldering | 300 | $^\circ C$ |
| T_{SOLD} | 1.6 mm (0.062in.) from Case for 10s | 260 | $^\circ C$ |
| M_d | Mounting Torque (TO-264) | 1.13/10 | Nm/lb.in |
| F_C | Mounting Force (PLUS247) | 20..120 /4.5..27 | N/lb |
| Weight | TO-264 | 10 | g |
| | PLUS247 | 6 | g |

TO-264 (IXFK)



PLUS247 (IXFX)



G = Gate D = Drain
 S = Source Tab = Drain

Features

- International Standard Packages
- Low Q_G
- Avalanche Rated
- Low Package Inductance

Advantages

- High Power Density
- Easy to Mount
- Space Savings

Applications

- Switch-Mode and Resonant-Mode Power Supplies
- DC-DC Converters
- PFC Circuits
- AC and DC Motor Drives
- Robotics and Servo Controls

| Symbol | Test Conditions ($T_J = 25^\circ C$ Unless Otherwise Specified) | Characteristic Values | | |
|--------------|---|-----------------------|------|--------------------|
| | | Min. | Typ. | Max. |
| BV_{DSS} | $V_{GS} = 0V$, $I_D = 1mA$ | 650 | | V |
| $V_{GS(th)}$ | $V_{DS} = V_{GS}$, $I_D = 4mA$ | 3.5 | | 5.0 V |
| I_{GSS} | $V_{GS} = \pm 30V$, $V_{DS} = 0V$ | | | ± 100 nA |
| I_{DSS} | $V_{DS} = V_{DSS}$, $V_{GS} = 0V$ $T_J = 125^\circ C$ | | | 50 μA 5 mA |
| $R_{DS(on)}$ | $V_{GS} = 10V$, $I_D = 0.5 \cdot I_{D25}$, Note 1 | | | 30 m Ω |

| Symbol | Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified) | Characteristic Values | | |
|-------------------------------------|--|--|------|-------------------------|
| | | Min. | Typ. | Max |
| g_{fs} | $V_{DS} = 10\text{V}$, $I_D = 0.5 \cdot I_{D25}$, Note 1 | 40 | 68 | S |
| R_{Gi} | Gate Input Resistance | | 0.7 | Ω |
| C_{iss} | $V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$, $f = 1\text{MHz}$ | | 10.8 | nF |
| C_{oss} | | | 6000 | pF |
| C_{rss} | | | 2.6 | pF |
| Effective Output Capacitance | | | | |
| $C_{o(er)}$ | Energy related | $V_{GS} = 0\text{V}$ $V_{DS} = 0.8 \cdot V_{DSS}$ | 365 | pF |
| $C_{o(tr)}$ | Time related | | 1500 | pF |
| $t_{d(on)}$ | Resistive Switching Times $V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 0.5 \cdot I_{D25}$ $R_G = 2\Omega$ (External) | | 37 | ns |
| t_r | | | 26 | ns |
| $t_{d(off)}$ | | | 90 | ns |
| t_f | | | 13 | ns |
| $Q_{g(on)}$ | $V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 0.5 \cdot I_{D25}$ | | 183 | nC |
| Q_{gs} | | | 60 | nC |
| Q_{gd} | | | 62 | nC |
| R_{thJC} | | | | 0.12 $^\circ\text{C/W}$ |
| R_{thCS} | | 0.15 | | $^\circ\text{C/W}$ |

Source-Drain Diode

| Symbol | Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified) | Characteristic Values | | |
|----------|---|-----------------------|------|---------------|
| | | Min. | Typ. | Max. |
| I_S | $V_{GS} = 0\text{V}$ | | | 100 A |
| I_{SM} | Repetitive, Pulse Width Limited by T_{JM} | | | 400 A |
| V_{SD} | $I_F = I_S$, $V_{GS} = 0\text{V}$, Note 1 | | | 1.4 V |
| t_{rr} | $I_F = 50\text{A}$, $-di/dt = 100\text{A}/\mu\text{s}$ $V_R = 100\text{V}$, $V_{GS} = 0\text{V}$ | | 200 | ns |
| Q_{RM} | | | 1.7 | μC |
| I_{RM} | | | 17.2 | A |

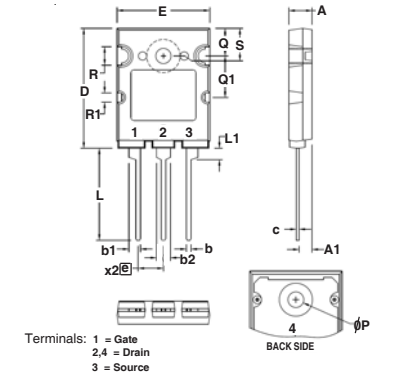
Note 1. Pulse test, $t \leq 300\mu\text{s}$, duty cycle, $d \leq 2\%$.

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

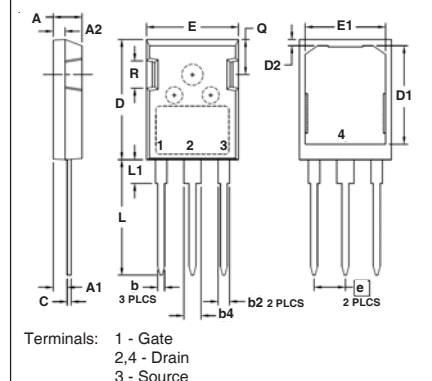
| | | | | | | | | | |
|-----------|-----------|-----------|-----------|--------------|--------------|--------------|--------------|--------------|-------------|
| 4,835,592 | 4,931,844 | 5,049,961 | 5,237,481 | 6,162,665 | 6,404,065 B1 | 6,683,344 | 6,727,585 | 7,005,734 B2 | 7,157,338B2 |
| 4,860,072 | 5,017,508 | 5,063,307 | 5,381,025 | 6,259,123 B1 | 6,534,343 | 6,710,405 B2 | 6,759,692 | 7,063,975 B2 | |
| 4,881,106 | 5,034,796 | 5,187,117 | 5,486,715 | 6,306,728 B1 | 6,583,505 | 6,710,463 | 6,771,478 B2 | 7,071,537 | |

TO-264 Outline



| SYM | INCHES | | MILLIMETERS | |
|-----------|----------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | .185 | .209 | 4.70 | 5.30 |
| A1 | .102 | .118 | 2.60 | 3.00 |
| b | .035 | .049 | 0.90 | 1.25 |
| b1 | .091 | .106 | 2.30 | 2.70 |
| b2 | .110 | .126 | 2.80 | 3.20 |
| c | .020 | .033 | 0.50 | 0.85 |
| D | 1.012 | 1.035 | 25.70 | 26.30 |
| E | .776 | .799 | 19.70 | 20.30 |
| e | .215 BSC | | 5.46 BSC | |
| L | .768 | .807 | 19.50 | 20.50 |
| L1 | .091 | .106 | 2.30 | 2.70 |
| ϕP | .122 | .138 | 3.10 | 3.50 |
| Q | .228 | .244 | 5.80 | 6.20 |
| Q1 | .346 | .362 | 8.80 | 9.20 |
| ϕR | .150 | .165 | 3.80 | 4.20 |
| $\phi R1$ | .071 | .087 | 1.80 | 2.20 |
| S | .228 | .244 | 5.80 | 6.20 |

PLUS247™ Outline



| SYM | INCHES | | MILLIMETERS | |
|-----|----------|------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | .190 | .205 | 4.83 | 5.21 |
| A1 | .090 | .100 | 2.29 | 2.54 |
| A2 | .075 | .085 | 1.91 | 2.16 |
| b | .045 | .055 | 1.14 | 1.40 |
| b2 | .075 | .087 | 1.91 | 2.20 |
| b4 | .115 | .126 | 2.92 | 3.20 |
| C | .024 | .031 | 0.61 | 0.80 |
| D | .819 | .840 | 20.80 | 21.34 |
| D1 | .650 | .690 | 16.51 | 17.53 |
| D2 | .035 | .050 | 0.89 | 1.27 |
| E | .620 | .635 | 15.75 | 16.13 |
| E1 | .520 | .560 | 13.08 | 14.22 |
| e | .215 BSC | | 5.45 BSC | |
| L | .780 | .810 | 19.81 | 20.57 |
| L1 | .150 | .170 | 3.81 | 4.32 |
| Q | .220 | .244 | 5.59 | 6.20 |
| R | .170 | .190 | 4.32 | 4.83 |

Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$

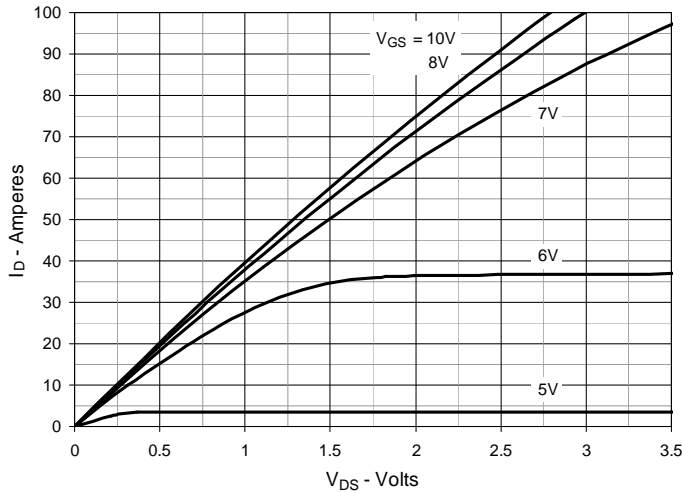


Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$

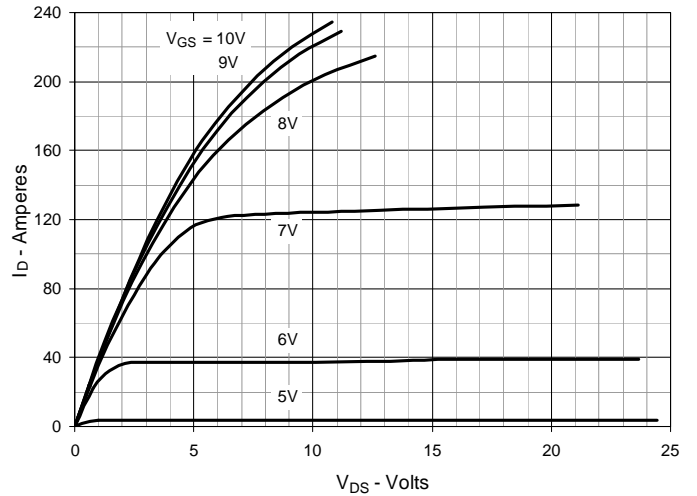


Fig. 3. Output Characteristics @ $T_J = 125^\circ\text{C}$

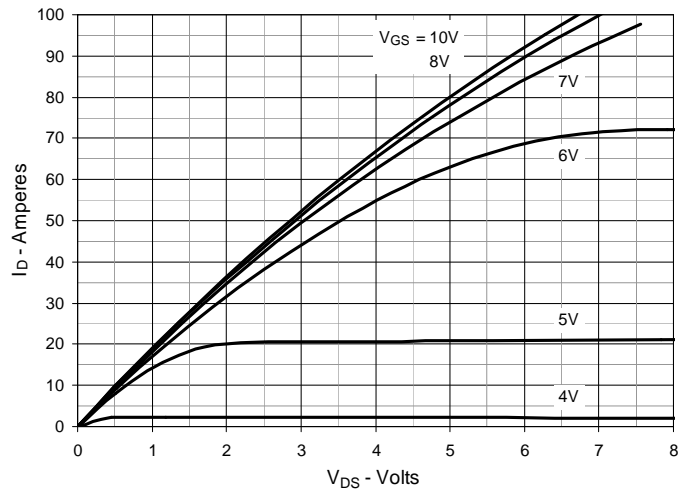


Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 50\text{A}$ Value vs. Junction Temperature

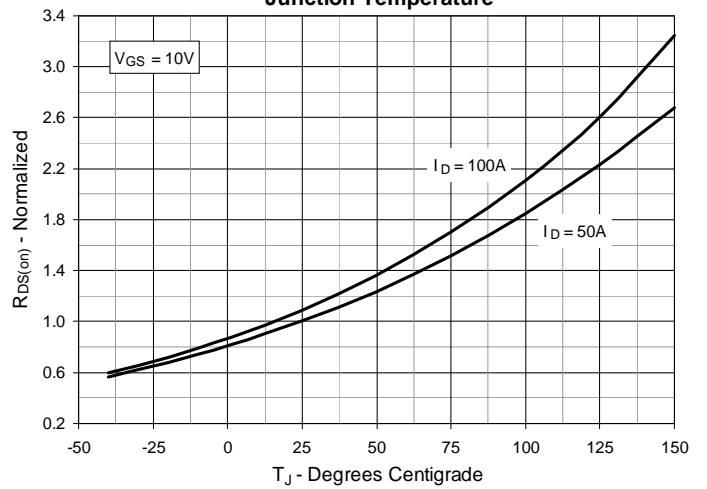


Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 50\text{A}$ Value vs. Drain Current

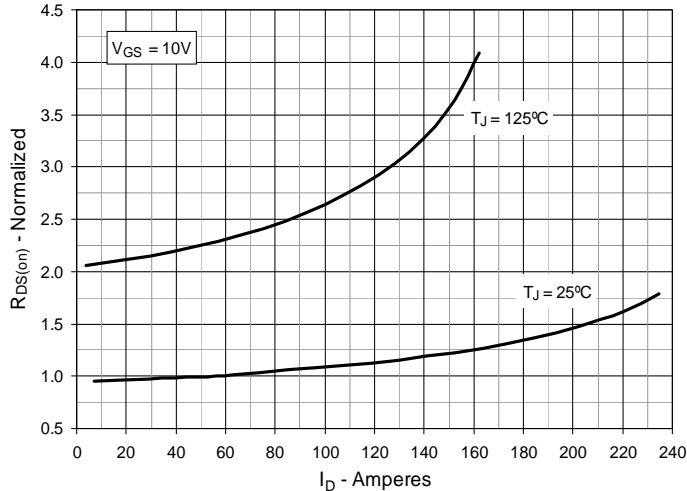


Fig. 6. Normalized Breakdown & Threshold Voltages vs. Junction Temperature

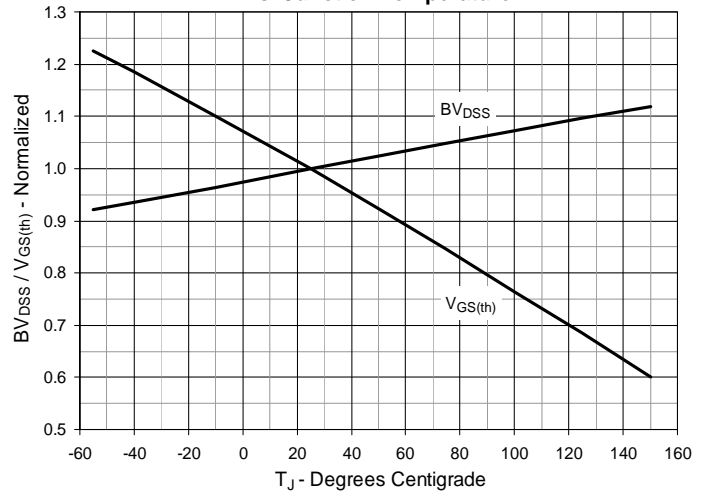


Fig. 7. Maximum Drain Current vs. Case Temperature

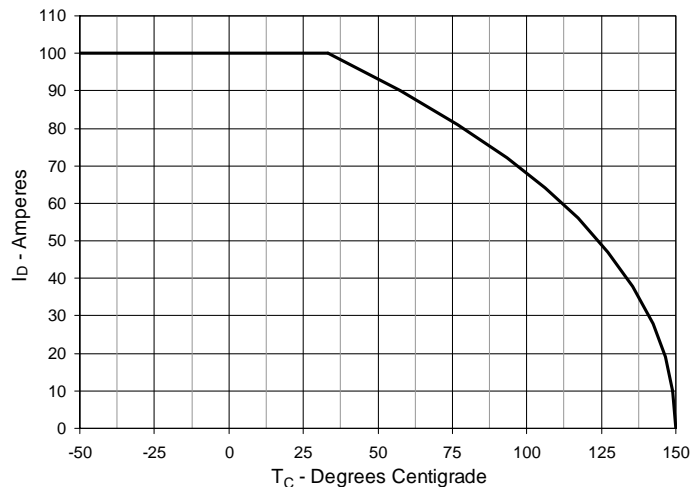


Fig. 8. Input Admittance

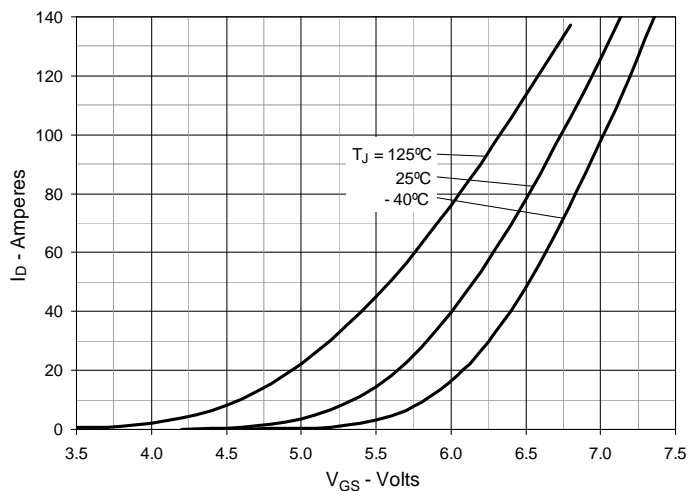


Fig. 9. Transconductance

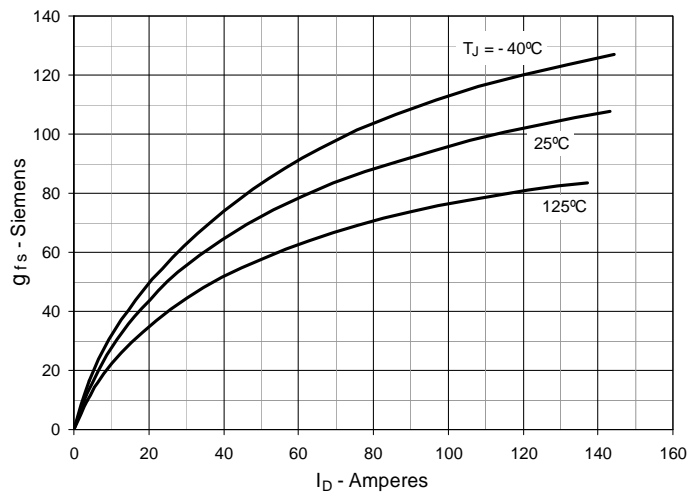


Fig. 10. Forward Voltage Drop of Intrinsic Diode

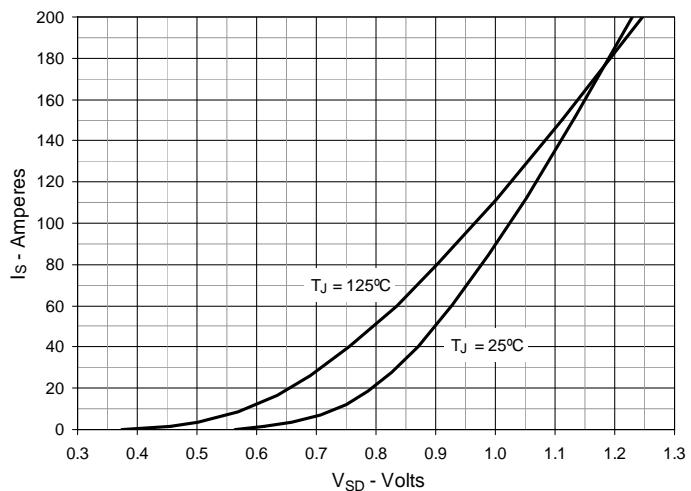


Fig. 11. Gate Charge

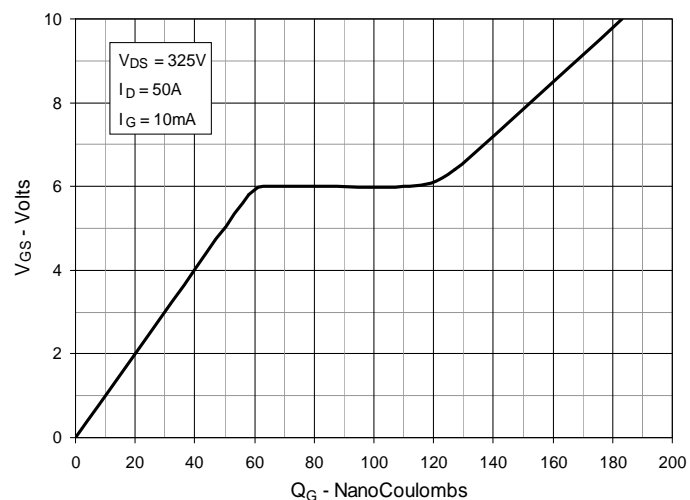


Fig. 12. Capacitance

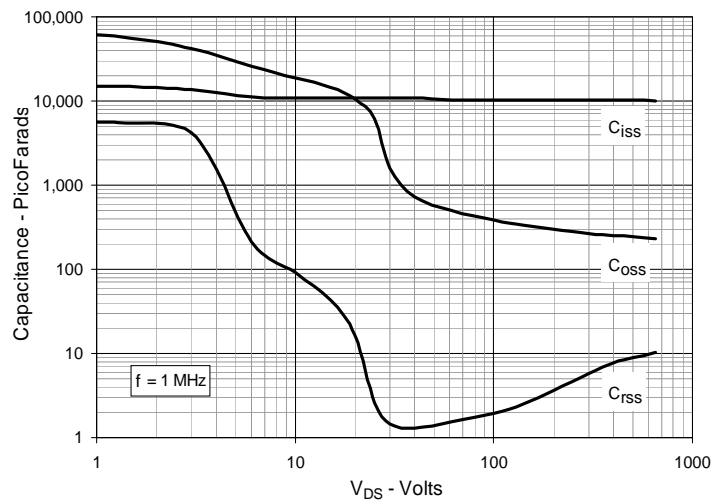


Fig. 13. Output Capacitance Stored Energy

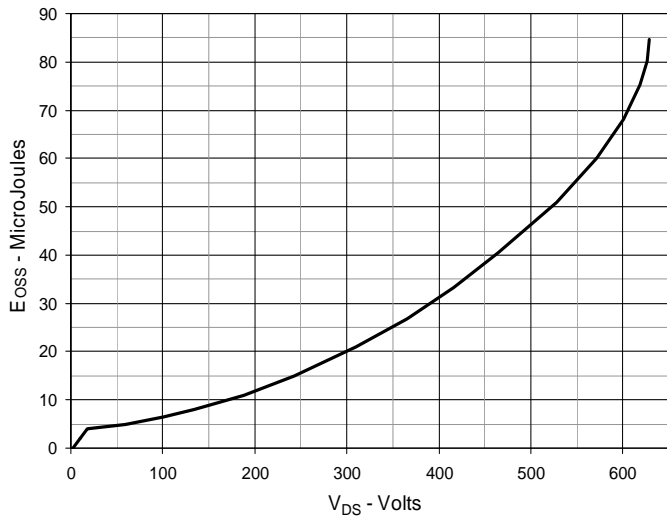


Fig. 14. Forward-Bias Safe Operating Area

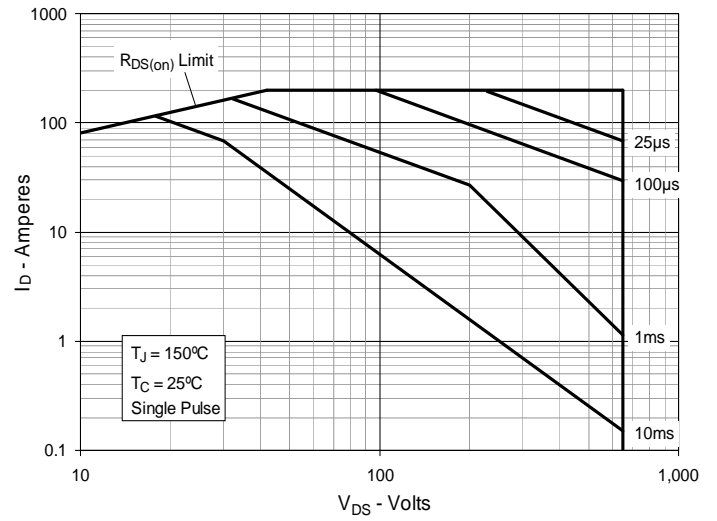
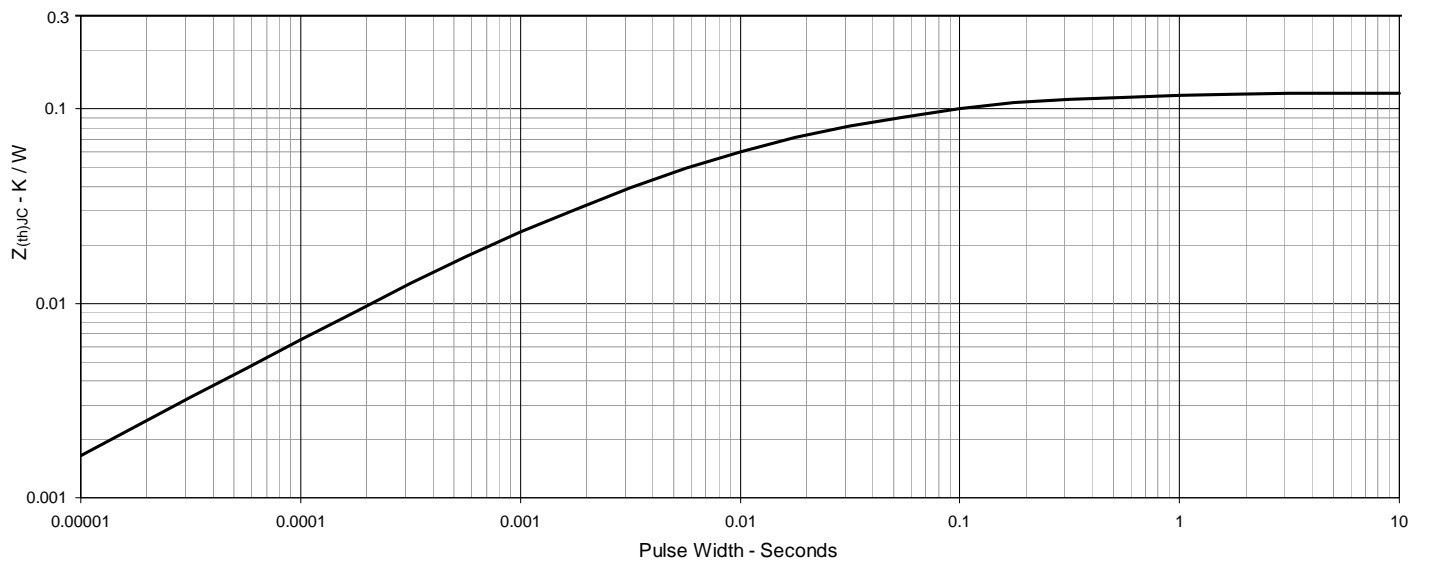


Fig. 15. Maximum Transient Thermal Impedance





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